

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT7159831

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
HIROAKI HIRAMATSU	09/03/2020
SHUHEI SAIDO	09/03/2020
TAKURO USHIDA	09/10/2020
RECEIVING PARTY DATA	
Name:	KOKUSAI ELECTRIC CORPORATION
Street Address:	3-4, KANDAKAJI-CHO
Internal Address:	CHIYODA-KU
City:	TOKYO
State/Country:	JAPAN
Postal Code:	1010045
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17582844
CORRESPONDENCE DATA	
Fax Number:	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Email:	jmd@usiplaw.com
Correspondent Name:	EDELL SHAPIRO & FINNAN LLC
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Address Line 2:	SUITE 750
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ATTORNEY DOCKET NUMBER:	1022.0120CON
NAME OF SUBMITTER:	PATRICK J. FINNAN
SIGNATURE:	/Patrick J. Finnann/
DATE SIGNED:	02/04/2022
Total Attachments: 6	
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**COMBINED DECLARATION (37 CFR 1.63) AND ASSIGNMENT
FOR UTILITY OR DESIGN APPLICATION**

Title of Invention	SUBSTRATE PROCESSING APPARATUS AND METHOD OF MANUFACTURING SEMICONDUCTOR DEVICE
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DECLARATION

As a below named inventor, I hereby declare that:

This declaration is directed to the above-identified application for United States Letters Patent and further identified by the Attorney Docket Number provided above in the header of this document.

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims.

I acknowledge the duty to disclose to the Office all information known to me to be material to patentability as defined in 37 CFR §1.56.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

ASSIGNMENT

For good and valuable consideration, the undersigned inventor(s), hereinafter individually or collectively referred to as "Assignor";

Hereby sell, assign and transfer to **KOKUSAI ELECTRIC CORPORATION**, a corporation organized and existing under the laws of Japan, having its principal place of business at c/o KOKUSAI ELECTRIC CORPORATION, 3-4, Kandakaji-cho, Chiyoda-ku, Tokyo 1010045, Japan, hereinafter "Assignee", its successors, assigns and legal representatives, the entire right, title and interest in and for the United States and all foreign countries, in and to any and all improvements which are disclosed in the above-identified application for United States Letters Patent, and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be filed in the United States and all foreign countries on said improvements;

Agree that said Assignee may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to but at the expense of said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and legal representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or legal representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment,

grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

LEGAL NAME OF JOINT INVENTOR

Inventor: Hiroaki HIRAMATSU

Having an address at: c/o KOKUSAI ELECTRIC CORPORATION, 2-1, Yasuuchi, Yatsuo-machi,
Toyama-shi, Toyama 9392393, Japan

Signature: _____ / Hiroaki Hiramatsu / _____ Date: September 3 , 2020

LEGAL NAME OF JOINT INVENTOR

Inventor: Shuhei SAIDO

Having an address at: c/o KOKUSAI ELECTRIC CORPORATION, 2-1, Yasuuchi, Yatsuo-machi,
Toyama-shi, Toyama 9392393, Japan

Signature: _____ Date: _____

LEGAL NAME OF JOINT INVENTOR

Inventor: Takuro USHIDA

Having an address at: c/o KOKUSAI ELECTRIC CORPORATION, 2-1, Yasuuchi, Yatsuo-machi,
Toyama-shi, Toyama 9392393, Japan

Signature: _____ Date: _____

Note: An application data sheet (PTO/SB/14 or equivalent), naming the entire inventive entity, either accompanies this form or was filed previously and thus is currently of record in the file.

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LEGAL NAME OF JOINT INVENTOR

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Signature: _____ Date: _____

LEGAL NAME OF JOINT INVENTOR

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Toyama-shi, Toyama 9392393, Japan

Signature: /Shuhei Saido/ _____ Date: September 3, 2020 _____

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LEGAL NAME OF JOINT INVENTOR

Inventor: Takuro USHIDA

Having an address at: c/o KOKUSAI ELECTRIC CORPORATION, 2-1, Yasuuchi, Yatsuo-machi,
Toyama-shi, Toyama 9392393, Japan

Signature: _____ / Takuro Ushida / _____ Date: _____ September 10 , 2020 _____

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